



Extract from our online catalogue:

esf-1/CF/A

Current to: 2024-02-26



The esf-1 fork sensor can detect labels reliably even at high label speeds.

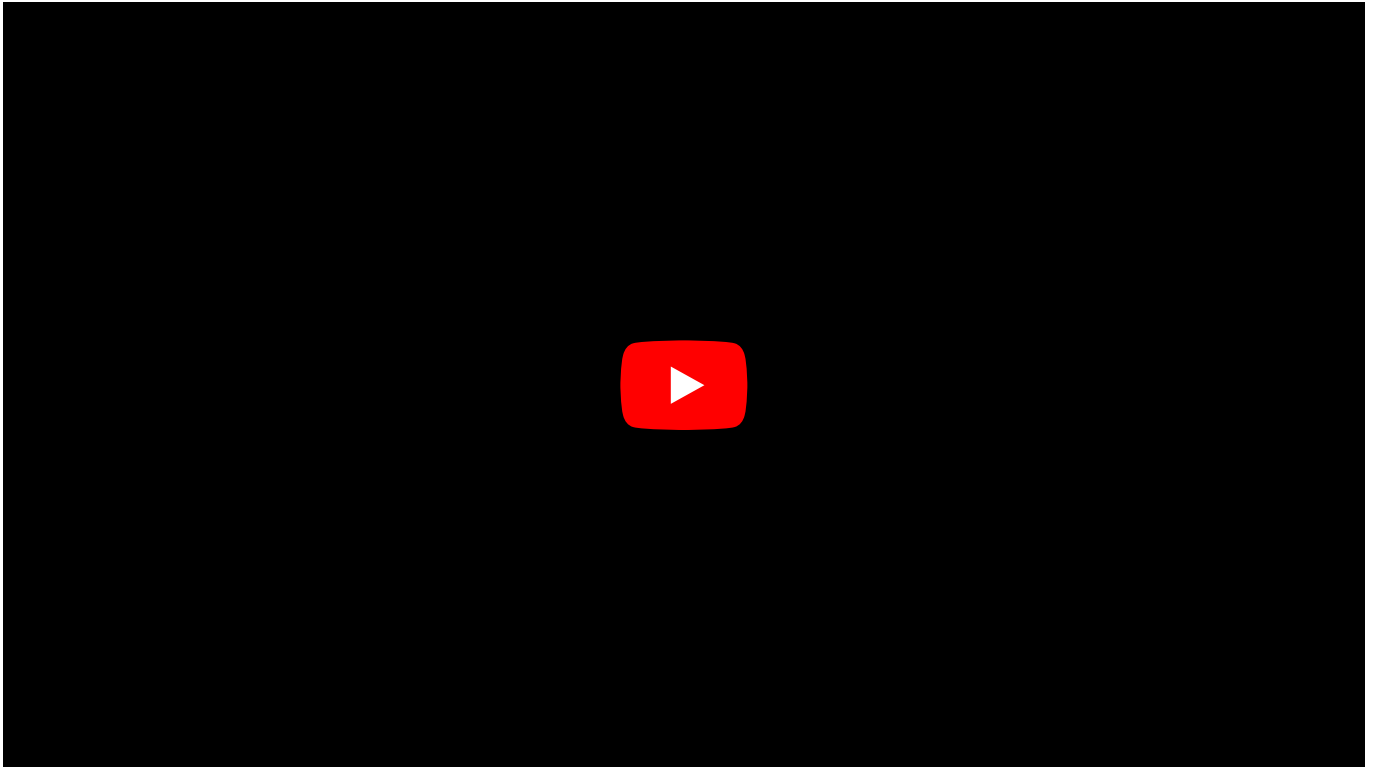
HIGHLIGHTS

- › 3 Teach-in methods › for the detection of labels even outside the standard
- › Response time < 300 μ s: › for use at high web speeds
- › Housing in fork format with very compact dimensions
- › QuickTeach › simplified Teach-in process
- › IO-Link interface › for support of the new industry standard
- › Smart Sensor Profile › more transparency between IO-Link Devices
- › Smart Sonic Function › recipe management via IO-Link
- › UL Listed to Canadian and US safety standards

BASICS

- › Label and splice sensor as a fork sensor
- › 2 switching outputs › for label/ splice detection and web break monitoring
- › 3 LEDs and 1 button on the top of the housing
- › Teach-in optionally via button or pin 5
- › LinkControl › as optional assistance for installation and commissioning

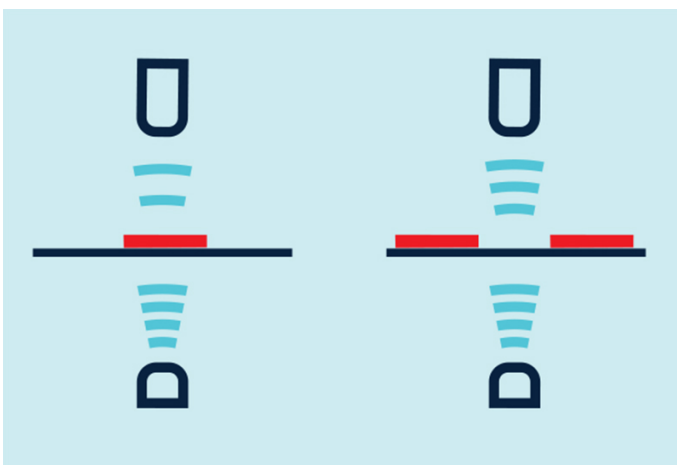
Description



The functional principle

Labels are guided through the fork. An ultrasonic transmitter in the lower leg of the fork beams a fast sequence of pulses through the backing material. The sound pulses cause the backing material to vibrate such that a greatly attenuated sound wave is beamed from the opposite side. The receiver in the upper leg of the fork receives this sound wave.

The backing material transmits a different signal level from the label. This signal difference is evaluated by the esf-1. The signal difference between the backing material and the label can be very slight. To ensure a reliable distinction, the esf-1 has to learn the label.



Backing material with a label provides an attenuated signal level

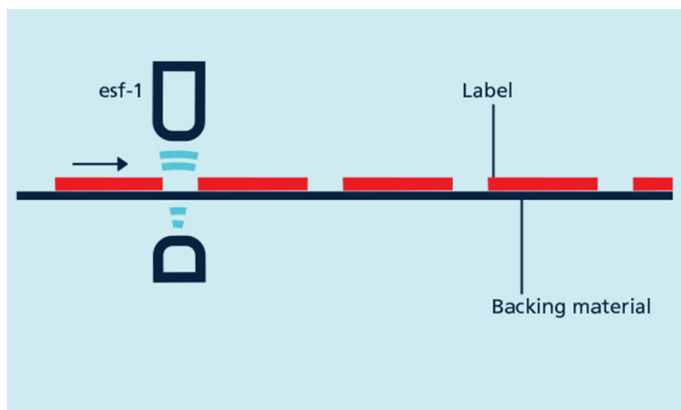
The esf-1

can reliably detect high-transparency, reflective materials as well as metallised labels and labels of any colour. The measurement cycle time automatically self-adjusts to the sound power required. For thin labels and backing materials, the esf-1 can work at its maximum speed, with a response time of $< 300 \mu\text{s}$.

To be able to detect special labels, for example labels with punches or perforations, there are three different Teach-in methods available.

A) Learn both backing material and label dynamically

During the Teach-in process, the backing material and its labels are guided through the fork at a constant speed. The esf-1 sensor automatically learns the signal level for the labels and for the gaps between the labels. This is the standard Teach-in for labels.



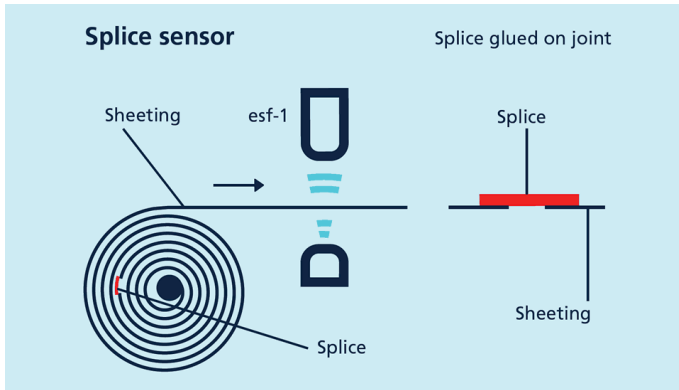
esf-1 as label sensor

B) Separate Teach-in for backing material and labels

The signal level difference for the backing material and labels might be very slight. In order to still scan labels with very little difference in signals, Teach-in for the signal levels is done separately: Teach-in is first done for the backing material and then for the label on it. The switching threshold then lies between these two signal levels.

C) Learn web material only

Web material is generally processed from a roll. The splice to be detected is hidden somewhere in the roll. There is a separate Teach-in method available for this purpose, in which only the sheeting is learned. The esf-1 detects the level difference at the splice and sets its output.



esf-1 as splice sensor

The Teach-in procedure

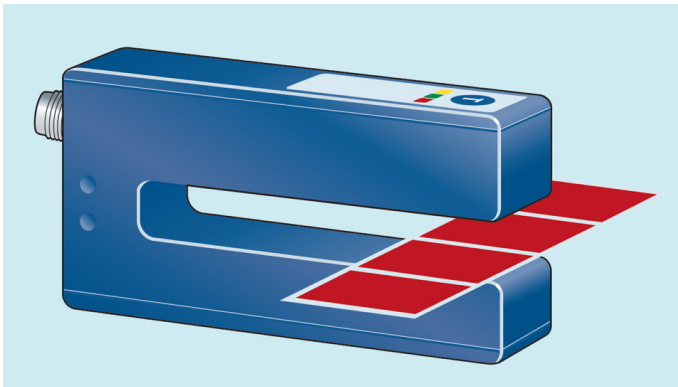
can optionally be carried out with the button on the top of the housing or with pin 5 on the unit's connector.

For QuickTeach

the esf-1 learns the material for the duration that the button is pushed or pin 5 is controlled.

With LinkControl

the esf-1 can optionally be parameterised. Measured values can also be shown graphically.



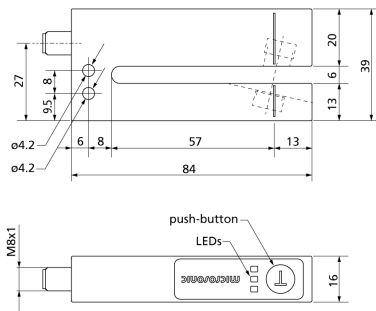
Labels are guided through the fork. The esf-1 reacts to the signal difference between the backing material and the label.

IO-Link

esf-1 ultrasonic label and splice sensors have a Push-Pull switching output and support IO-Link in version 1.1.

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scale drawing



detection zone



1 x Push-Pull

working range	sheeting with weights of <math>< 20 \text{ g/m}^2</math> up to >> 400 g/m^2, metal-laminated sheets and films up to 0.2 mm thick, self-adhesive films, labels on backing material
design	fork-like
operating mode	IO-Link label/splice detection
particularities	IO-Link Smart Sensor Profile UL Listed

ultrasonic-specific

means of measurement	pulse operation with amplitude evaluation
transducer frequency	500 kHz

electrical data

operating voltage U_b	20 - 30 V d.c., reverse polarity protection
voltage ripple	$\pm 10 \%$
no-load current consumption	$\leq 50 \text{ mA}$
type of connection	4-pin M8 initiator plug

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outputs

output 1	switching output label/splice detected Push-Pull, $U_B=3\text{ V}$, $-U_B+3\text{ V}$, $I_{\max} = 100\text{ mA}$ NOC/NCC adjustable, short-circuit-proof
response time	300 μs up to 2,25 ms, dependent on the material
delay prior to availability	< 300 ms

inputs

input 1	com input teach-in input
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IO-Link

product name	esf-1/CF/A
product ID	16951
SIO mode support	yes
COM mode	COM2 (38,4 kBaud)
min. cycle time	4 ms
format of process data	32 Bit PDI
content of process data	Bit 0: initial state Pin 4; Bit 1: initial state Pin 2; Bit 2: web break; Bit 8-15: scale (Int. 8); Bit 16-31: measured value (Int. 16)
ISDU paramter	Identification, switched output, add-ons, temperature compensation, operation
system commands	SP1 Teach-in, SP2 Teach-in, factory settings
Smart Sensor Profile	yes
IODD version	IODD version 1.1

housing

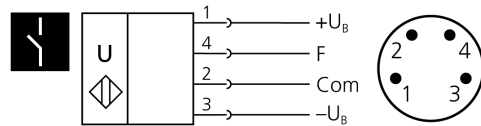
fork width	6 mm
fork depth	70 mm
material	aluminium anodized
ultrasonic transducer	polyurethane foam, epoxy resin with glass contents
class of protection to EN 60529	IP 65
operating temperature	+5°C to +60°C
storage temperature	-40°C to +85°C
weight	80 g

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technical features/characteristics

controls	1 push-button
scope for settings	Teach-in und QuickTeach über Taster Teach-in über Com-Eingang an Pin 2 LCA-2 mit LinkControl IO-Link
particularities	IO-Link Smart Sensor Profile UL Listed

pin assignment



order no.

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